

Notice of References Cited	Application/Control No. 09/682,347	Applicant(s)/Patent Under Reexamination LESLIE ET AL.	
	Examiner Hugh Jones	Art Unit 2128	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US- 6,694,355	2-2004	Baker	709/217
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
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	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
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	R					
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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Lee et al. "Application of a CFD tool for system level thermal simulation" IEEE Trans. Components
		pp. 564-572; 12/1994.
	W	An investigation of thermal enhancement Lee on flip chip BGA packages using CFD tool;
		IEEE Trans. Components; pp. 481-489; 9/2000.

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.